

Silicon NPN Phototransistor

Version 1.3

SFH 3400



Features:

- **Spectral range of sensitivity:** (typ) 460 ... 1080 nm
- **Package:** Smart DIL
- **Special:** High linearity
- Available only on tape and reel
- The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.

Applications

- Photointerrupters
- Industrial electronics
- For control and drive circuits
- Ambient light detector

Ordering Information

Type:	Photocurrent I_{PCE} [μ A] $\lambda = 950 \text{ nm}$, $E_e = 0.1 \text{ mW/cm}^2$, $V_{CE} = 5 \text{ V}$	Ordering Code
SFH 3400	63 ... 320	Q65110A2629
SFH 3400-2/3	100 ... 320	Q65110A2634

Maximum Ratings ($T_A = 25\text{ °C}$)

Parameter	Symbol	Values	Unit
Operating and storage temperature range	$T_{op}; T_{stg}$	-40 ... 100	°C
Collector-emitter voltage	V_{CE}	20	V
Collector-emitter voltage ($t < 2\text{ min}$)	V_{CE}	70	V
Collector current	I_C	50	mA
Collector surge current ($\tau < 10\text{ }\mu\text{s}$)	I_{CS}	100	mA
Emitter-collector voltage	V_{EC}	7	V
Total Power dissipation	P_{tot}	120	mW
ESD withstand voltage (acc. to ANSI/ ESDA/ JEDEC JS-001 - HBM)	V_{ESD}	2000	V
Thermal resistance for mounting on pcb	R_{thJA}	450	K/W

Characteristics ($T_A = 25\text{ °C}$)

Parameter		Symbol	Values	Unit
Wavelength of max. sensitivity	(typ)	$\lambda_{S\text{ max}}$	850	nm
Spectral range of sensitivity	(typ)	$\lambda_{10\%}$	(typ) 460 ... 1080	nm
Radiant sensitive area	(typ)	A	0.55	mm ²
Dimensions of chip area	(typ)	L x W	(typ) 1 x 1	mm x mm
Half angle	(typ)	φ	± 60	°
Capacitance ($V_{CE} = 5\text{ V}$, $f = 1\text{ MHz}$, $E = 0$)	(typ)	C_{CE}	10	pF
Dark current ($V_{CE} = 10\text{ V}$, $E = 0$)	(typ (max))	I_{CE0}	3 (≤ 100)	nA

Grouping ($T_A = 25\text{ °C}$, $\lambda = 950\text{ nm}$)

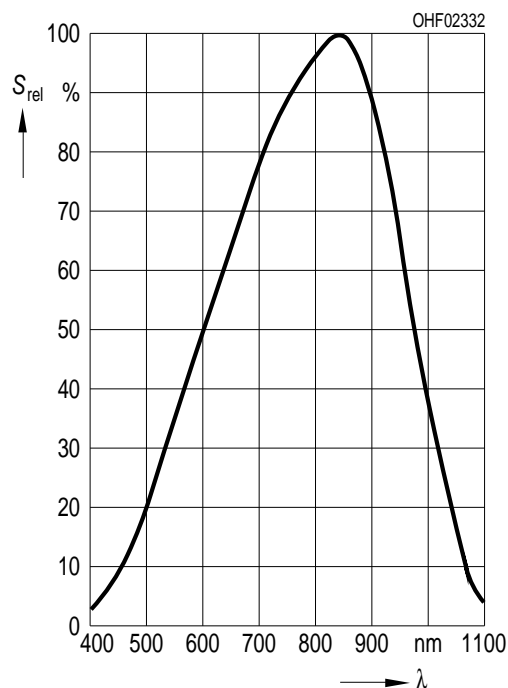
Group	Min Photocurrent $E_e = 0.1\text{ mW/cm}^2$, $V_{CE} = 5\text{ V}$ $I_{PCE, min}$ [μA]	Max Photocurrent $E_e = 0.1\text{ mW/cm}^2$, $V_{CE} = 5\text{ V}$ $I_{PCE, max}$ [μA]	Typ Photocurrent $E_V = 1000\text{ lx, Std. Light A, } V_{CE} = 5\text{ V}$ I_{PCE} [μA]	Rise and fall time $I_C = 1\text{ mA, } V_{CC} = 5\text{ V, } R_L = 1\text{ k}\Omega$ t_r, t_f [μs]
SFH 3400-1	63	125	1650	16
SFH 3400-2	100	200	2600	24
SFH 3400-3	160	320	4200	34

Group	Collector-emitter saturation voltage $I_C = I_{PCEmin} \times 0.3, E_e = 0.1\text{ mW/cm}^2$ V_{CEsat} [mV]
SFH 3400-1	170
SFH 3400-2	170
SFH 3400-3	170

Note.: I_{PCEmin} is the min. photocurrent of the specified group.

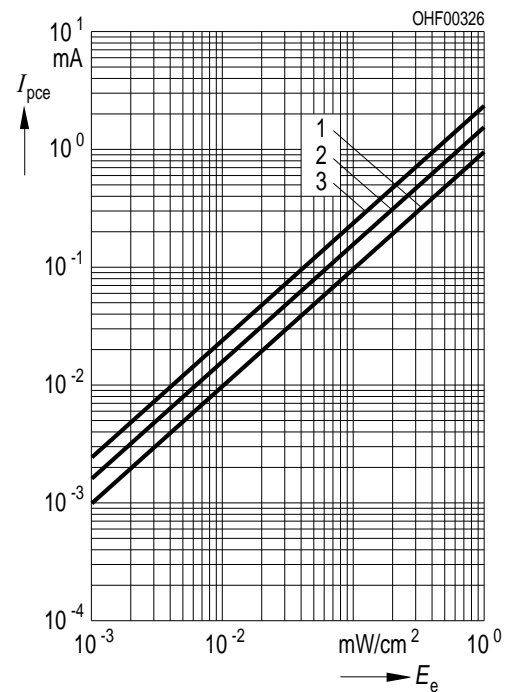
Relative Spectral Sensitivity ^{1) page 12}

$$S_{rel} = f(\lambda)$$



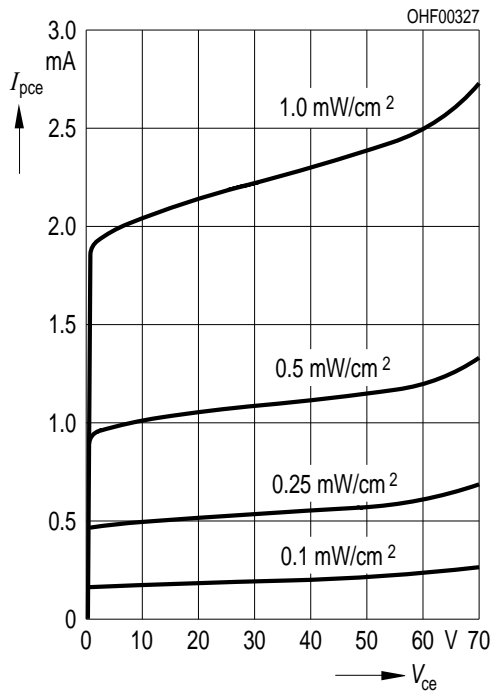
Photocurrent ^{1) page 12}

$$I_{PCE} = f(E_e), V_{CE} = 5\text{ V}$$



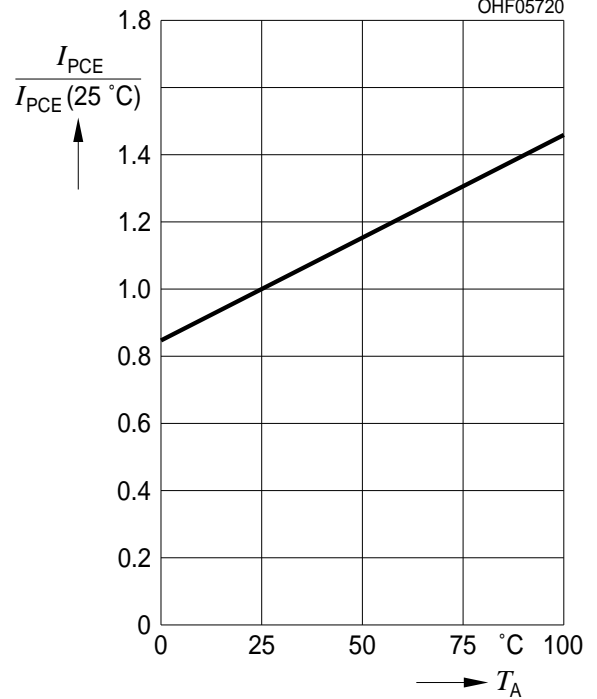
Photocurrent ^{1) page 12}

$I_{PCE} = f(V_{CE}), E_e = \text{Parameter}$



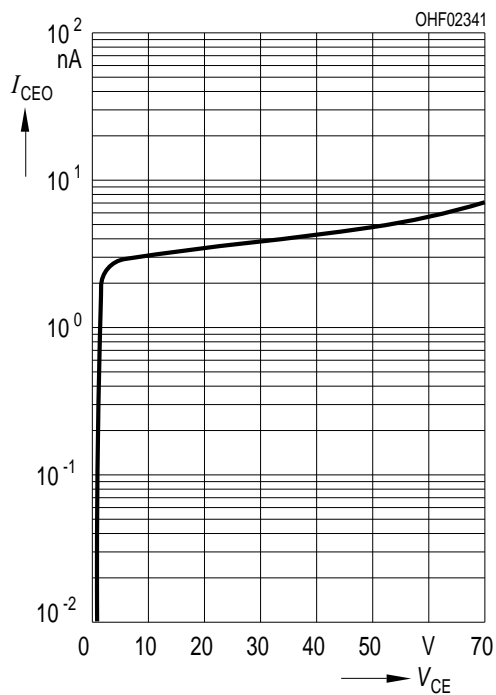
Photocurrent ^{1) page 12}

$I_{PCE} / I_{PCE}(25^\circ\text{C}) = f(T_A), V_{CE} = 5\text{ V}$



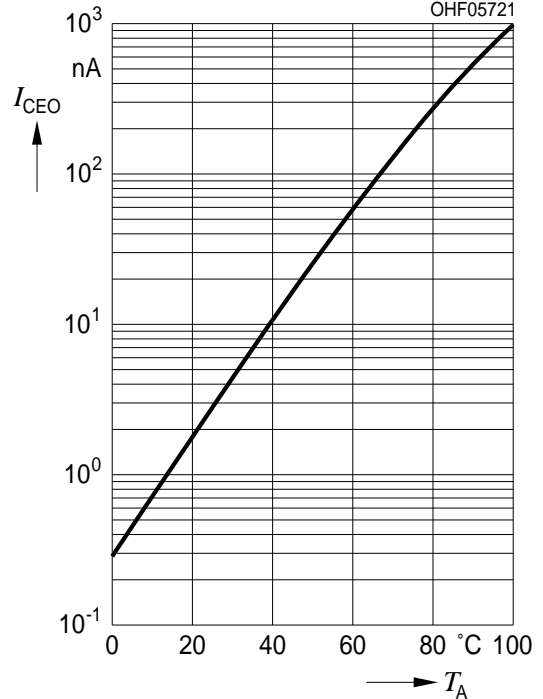
Dark Current ^{1) page 12}

$I_{CEO} = f(V_{CE}), E = 0$



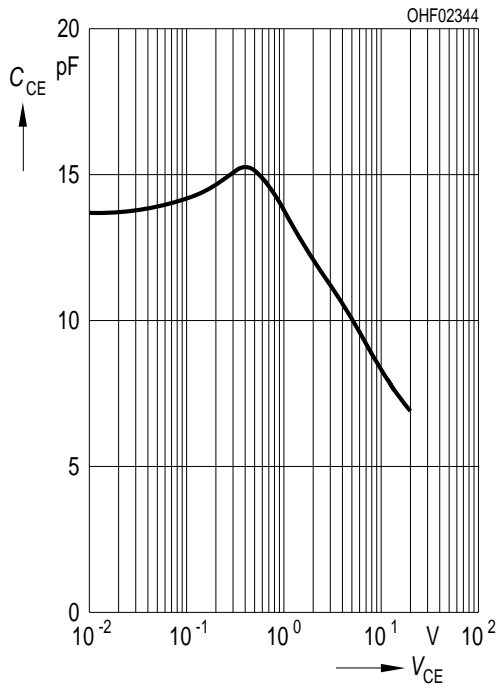
Dark Current ^{1) page 12}

$I_{CEO} = f(T_A), E = 0$



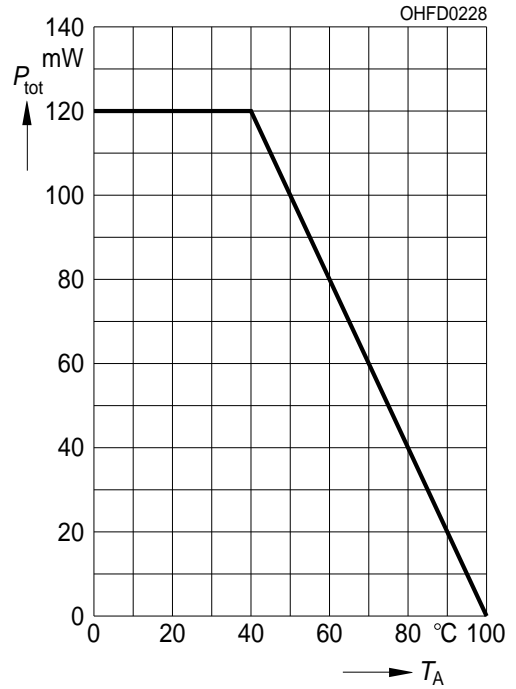
Collector-Emitter Capacitance ^{1) page 12}

$C_{CE} = f(V_{CE}), f = 1 \text{ MHz}, E = 0$



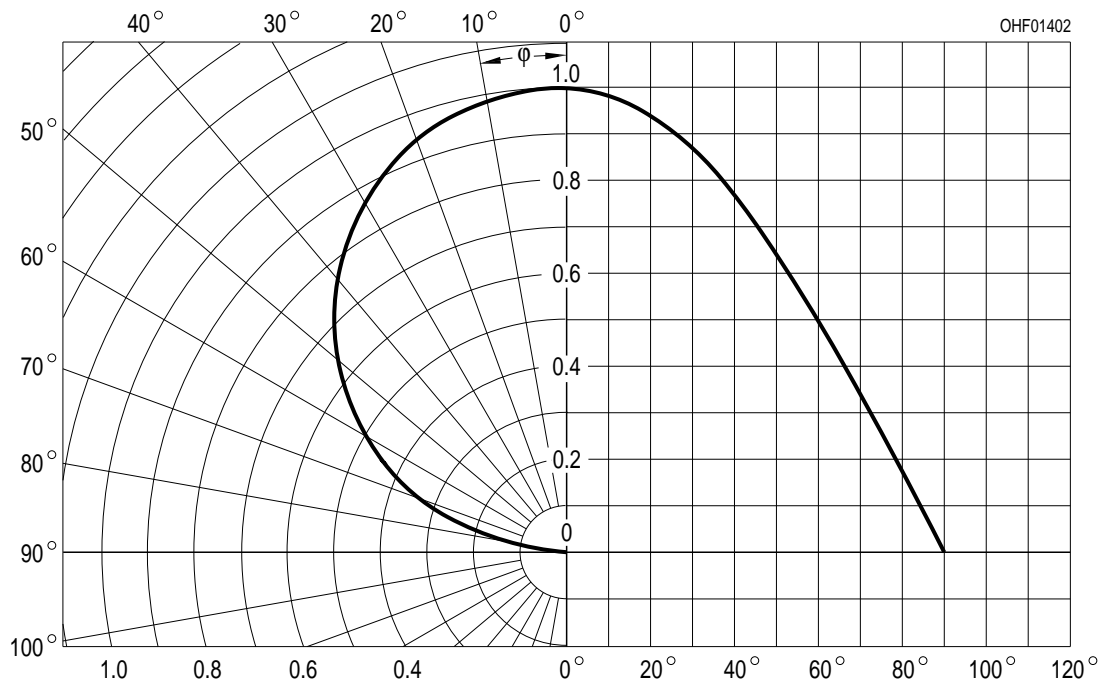
Power Consumption

$P_{tot} = f(T_A)$

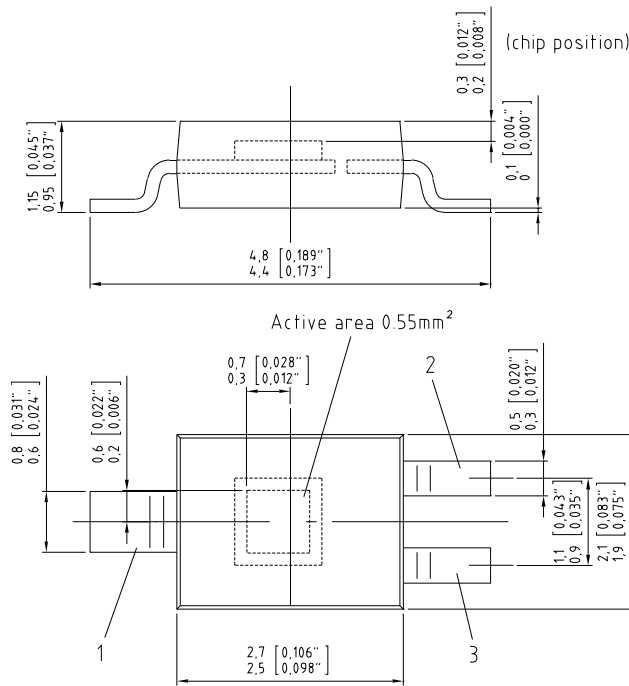


Directional Characteristics ^{1) page 12}

$S_{rel} = f(\phi)$



Package Outline



Dimensions in mm (inch).

Pinning

Pin	Description
1	collector
2	n.c.
3	emitter

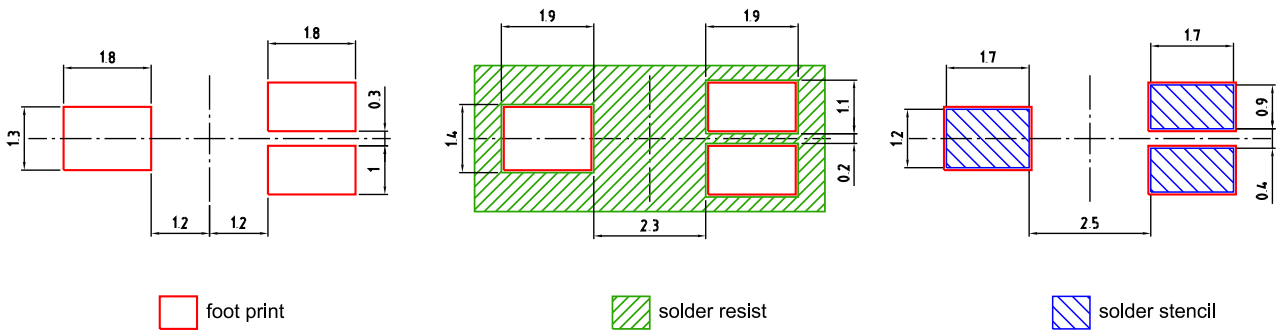
Package

Smart DIL

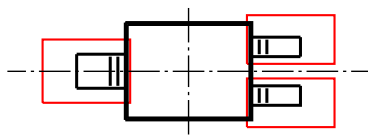
Approximate Weight:

12 mg

Recommended Solder Pad



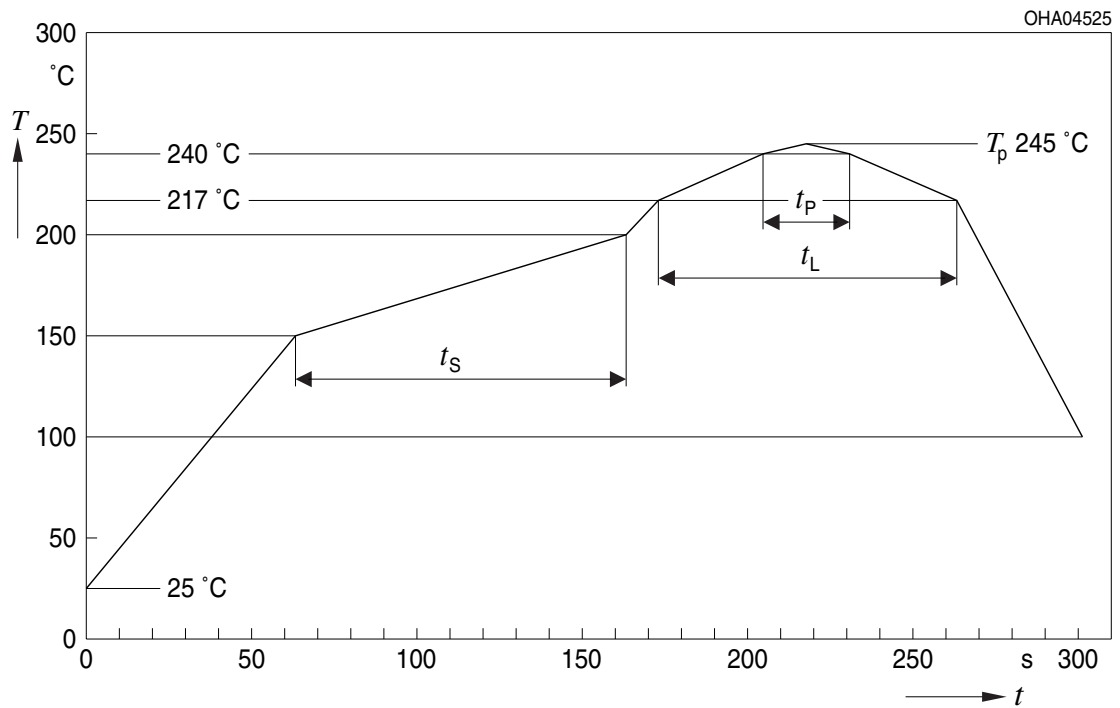
Component Location on Pad



E062.3010.216-01

Reflow Soldering Profile

Product complies to MSL Level 4 acc. to JEDEC J-STD-020D.01



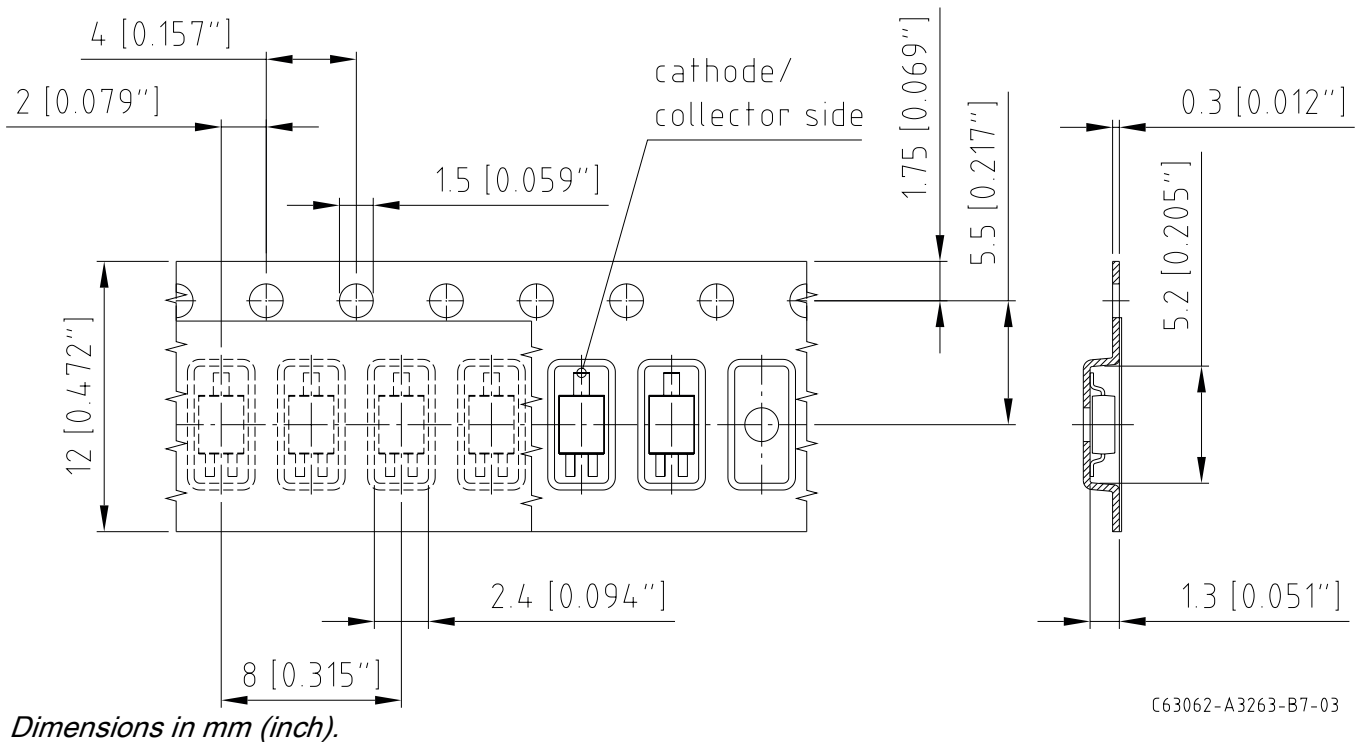
OHA04612

Profile Feature Profil-Charakteristik	Symbol Symbol	Pb-Free (SnAgCu) Assembly			Unit Einheit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature $T_P - 5$ K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component

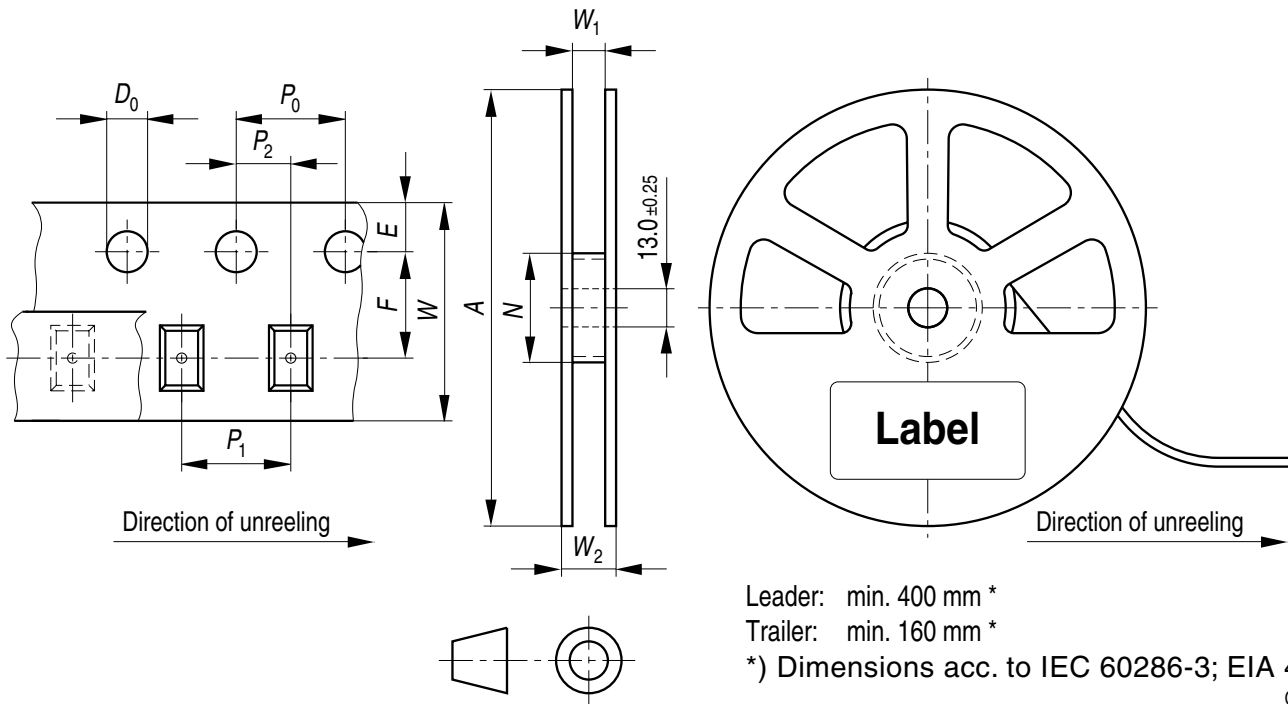
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping



Tape and Reel

12 mm tape with 2000 pcs. on \varnothing 180 mm reel



Leader: min. 400 mm *

Trailer: min. 160 mm *

*) Dimensions acc. to IEC 60286-3; EIA 481-D

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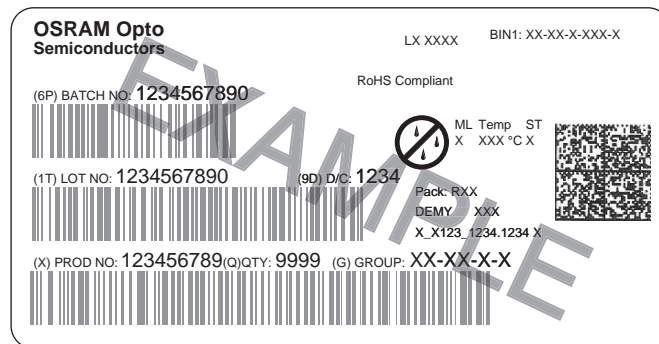
Tape dimensions [mm]

W	P ₀	P ₁	P ₂	D ₀	E	F
12 + 0.3 / - 0.1	4 ± 0.1	4 ± 0.1 or 8 ± 0.1	2 ± 0.05	1.5 ± 0.1	1.75 ± 0.1	5.5 ± 0.05

Reel dimensions [mm]

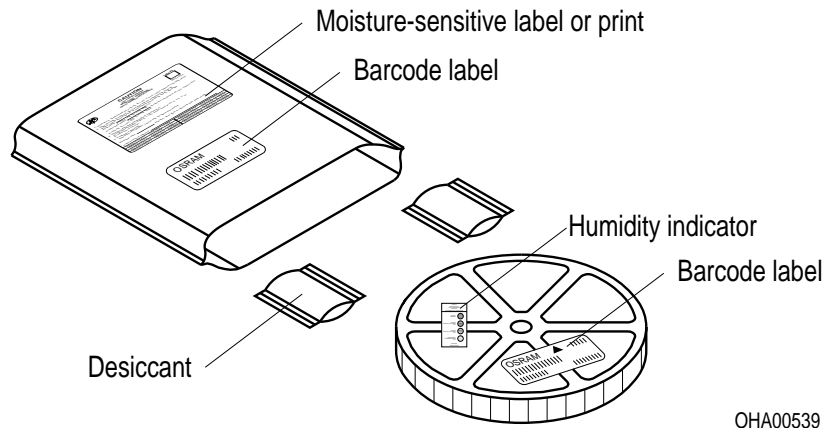
A	W	N _{min}	W ₁	W _{2max}
180	12	60	12.4 + 2	18.4

Barcode-Product-Label (BPL)



OHA04563

Dry Packing Process and Materials

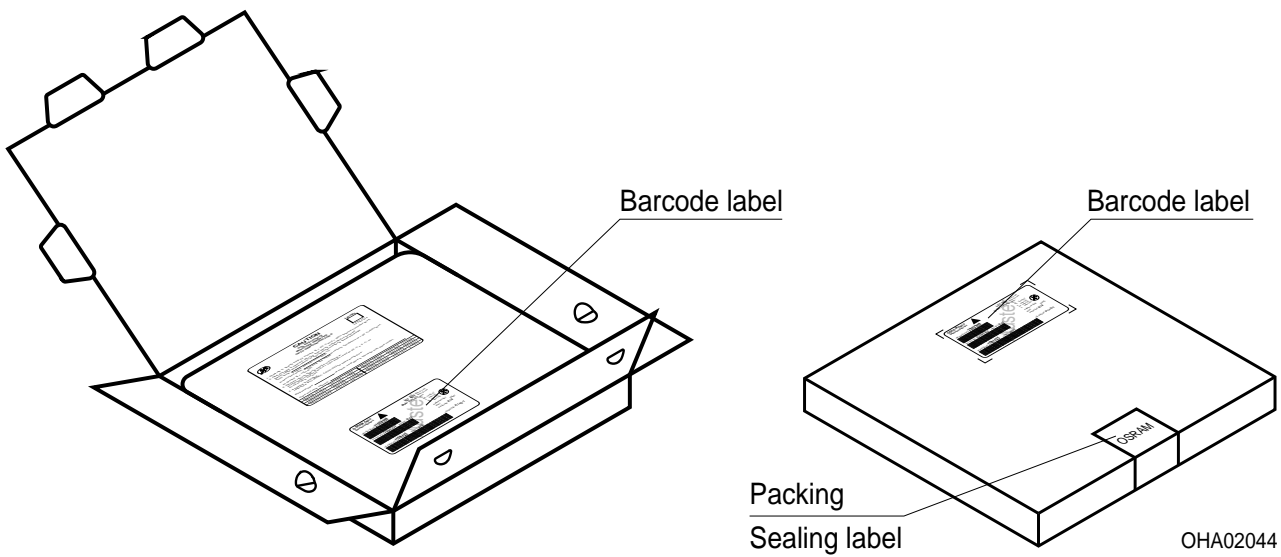


OHA00539

Note:

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card. Regarding dry pack you will find further information in the internet. Here you will also find the normative references like JEDEC.

Transportation Packing and Materials



OHA02044

Dimensions of transportation box in mm

Width	Length	Height
195 ± 5	195 ± 5	30 ± 5

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.

Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version in the Internet.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose!

Critical components* may only be used in life-support devices** or systems with the express written approval of OSRAM OS.

*) A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

**) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.

Glossary

- ¹⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

Published by OSRAM Opto Semiconductors GmbH
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